

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

TSSOP

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**TOTAL MASS (g) : 0.072411**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.003739	1000000	51635.5625		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.024098	962000	332793.1875		
		Iron (Fe)	7439-89-6	0.000000	0	0		
		Phosphorus (P)	7723-14-0	0.000000	0	0		
		Zinc (Zn)	7440-66-6	0.000000	0	0		
		Nickel (Ni)	7440-02-0	0.000751	30000	10371.3037109		
		Silicon (Si)	7440-21-3	0.000163	1500	524.779663086		
		Magnesium (Mg)	7439-95-4	0.000038	1500	524.779663086		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.025050</b>	<b>1000000</b>	<b>345940.28125</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.001770	1000000	24448.2285156		
		<b>External Plating Total:</b>				<b>0.001770</b>	<b>1000000</b>	<b>24448.2285156</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000000	0	0		
<b>Internal Plating Total:</b>				<b>0.000000</b>	<b>0</b>	<b>0</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001052	750000	14528.1113281		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000351	250000	4847.30712891		
<b>Die Attach Total:</b>				<b>0.001403</b>	<b>1000000</b>	<b>19375.4199219</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.005414	135000	74767.296875		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.034486	860000	476251.40625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000201	5000	2775.80859375		
		<b>Encapsulation Total:</b>				<b>0.040101</b>	<b>1000000</b>	<b>553794.5</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000348	1000000	4805.87744141		
					<b>TOTAL MASS (g) :</b>	<b>0.072411</b>		